



**Architecture, Operational Capabilities and features of the
VNH2SP30-E Motor Driver**

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February 22,2026

1.0 Introduction

1.1 Background of DC Motor Control

DC (Direct current) motors and motor drivers are known for using mostly in robotics, automotive systems and industrial automation because of their controllability, and high torque characteristics. As controlling a motor needs the regulation of both speed and its direction and which cant be done by connecting them directly thats where the motor driver helps.when its about controlling motors bidirectional rotation an H bridge topology is one of the best choice. H bridge topology comes with four switching elements arranged in a way which allows the polarity across the motor terminal to be reversed by activating specific switches. For example: clockwise and counterclockwise rotation, braking modes, free wheeling operation. H bridges as usually made usually by using MOSFETs or bipolar transistors.which come with some complexity and challenges like cross conduction risk, thermal instability, short circuit issues and gate driving challenge. These challenges make it unreliable when used for automotive application and show risks in high current flow but mostly those issues occur when the design is discrete.

1.2 Need for Integrated Smart Motor Drivers

Nowadays a compact, protected, and highly efficient motor driver is needed for embedded systems. For these reasons integrated motor driver ICs come with high and low side MOSFETs, gate drive circuitry,Thermal shutdown system, high current protection, over and under voltage protection. The VN2SP30-E motor driver comes with all those features which makes it a perfect choice for modern days advanced robotics, automotive systems and industrial automation. This is developed by STMicroelectronics where they integrated H-bridge with high current application. This device supports:

- Supply voltage up to 41v
- Output current up to 30A
- Integrated current sensing
- PWM control up to 20 kHz
- Multiple protection mechanism (For example: mostly comes with internal reverse polarity protection)

This report provides details and features of the VN2SP30-E motor driver, including its Internal architecture examination, Electrical characteristic breakdown, Switching behavior analysis, Protection mechanism evaluation, Thermal performance assessment, Application design guidelines.

2.0 Device Overview

2.1 General Description

The VNH2SP30-E is a high current H bridge motor driver for automotive and industrial motor control applications. It is capable of driving DC motors with high efficiency along with multiple protection and diagnostic capability. It integrates two high and low side MOSFETs, protection logic, Current sensing feature, gate driver circuitry and diagnostics outputs. This feature reduces external components and makes the pcb design simple instead of a discrete H bridge design.

2.2 Technological platform and Mechanical structure

The VNH2SP30-E comes with ST's proprietary VIPower™ M0 technology which adds power MOSFET structure, CMOS logic circuitry, analog sensing blocks and protection mechanism. This hybrid integration allows high current power stages to work with precise low voltage control logic on a single silicon die. Its MOSFET structure is based on a STripFET™ technology, which optimizes it for, low RDS (on), high current handling capability, reduced conduction losses with improved thermal performance. Those technologies integration allows that motor driver to maintain a low conduction loss even if it is at high load current which is mostly critical for efficiency and thermal stability. This device is housed in a MultiPowerSO-30 surface-mount package. Which includes high current application, exposed thermal pads, multiple ground pins, wide copper lead frame for the spreading of heat and its thermal slug at the bottom of the package plays a critical role in heat dissipation generated by power MOSFET conduction losses. This device needs a proper PCB layout for its efficient thermal dissipation, minimizing its parasitic inductance and stable switching behaviour. To reduce its resistive losses and to prevent localized heating its high current traces must be connected to substantial copper areas.

2.3 Electrical capability and automotive qualification

The VNH2SP30-Es max supply voltage is 41v with continuous output current up to 30A and PWM frequency support up to 20kHz. Its peak current capability is significantly higher for short duration with integrated current sense proportional output and built-in fault detection and protection. This motor driver is highly capable for automotive actuator systems, high torque robotics motors and battery power motor platforms.

Its "E" suffix indicates it is for automotive grade qualification. As this device complies with AEC-Q100 reliability standards which makes it capable and tested for temperature cycling, mechanical stress, electrical overstress and long term reliability for critical conditions.

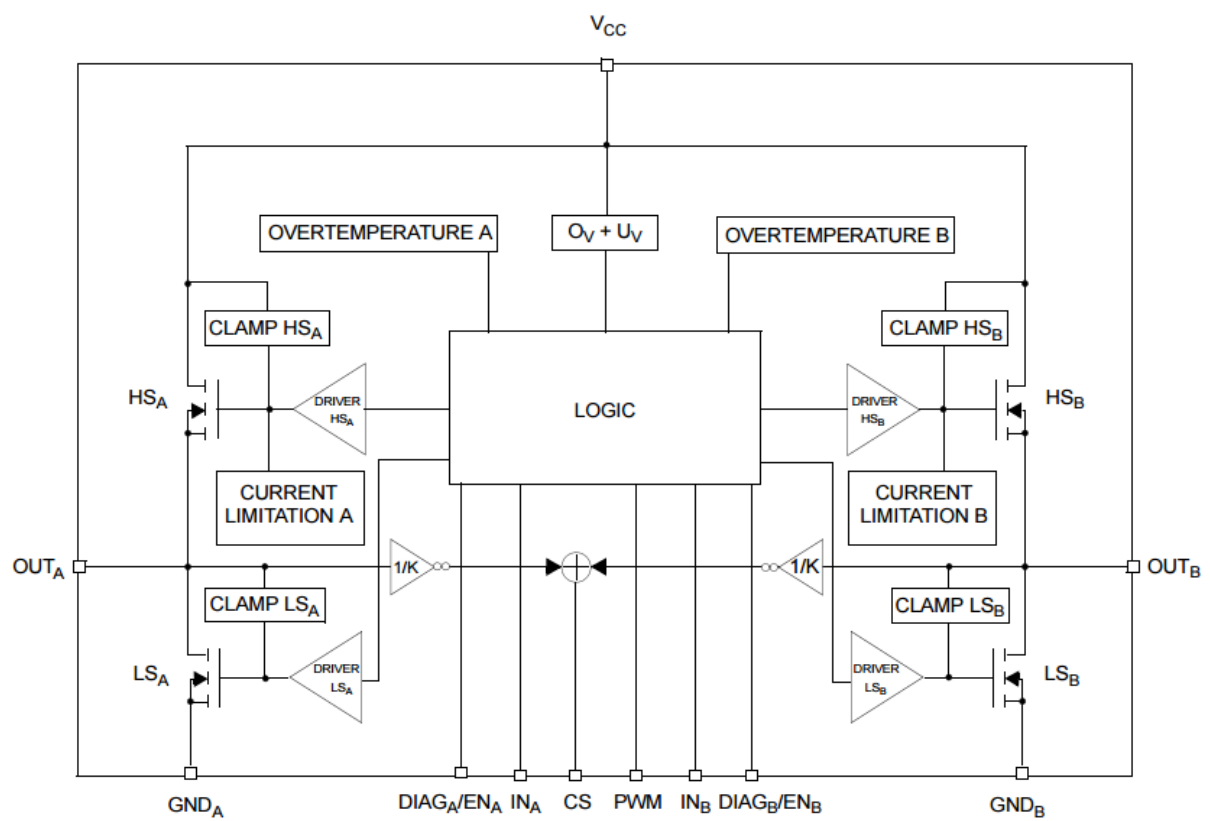


Fig 1 Block Diagram

3.0 Internal Architecture Analysis

3.1 Functional Block Overview

The VNH2SP30-E motor driver is divided internally in 5 major blocks. They are

1. High side power MOSFET drivers.
2. Low side power MOSFET drivers.
3. Gate drive and control logic.
4. Protection circuitry
5. Current sensing and diagnostic block.

These subsystems operate together to provide controlled bidirectional motor driving.

3.2 H-Bridge Power Stage Structure

The VNH2SP30-E motor drivers power stage is consist of four MOSFET arranged in a H-bridge configuration

High-side A (HS_A)

Low-side A (LS_A)

High-side B (HS_B)

Low-side B (LS_B)

So, the motor should be connected in between outputs OUTA and OUTB.

For forward operation,

(HS_A) and (LS_B) are turned on

(HS_B) and (LS_A) are turned off

Current flows from VCC to HS_A to Motor to LS_B and GND.

For reverse operation,

(HS_B) and (LS_A) are turned on

(HS_A) and (LS_B) are turned off

Current directions through the motor are reversed.

3.3 High and Low Side Driver Architecture

To drive the high side MOSFETs it requires gate voltages which should be higher than the supply voltage. As this device integrates both charge pump circuitry and gate voltage boosting mechanism. This integration allows the high side MOSFET gate to be driven above VCC and that thing ensures full enhancement of MOSFET, low RDS on and also it reduces conduction losses.

On the other hand the low side MOSFETs are referenced to ground and are much easier to drive. But it must have to handle high current, rapid switching transitions along with free wheeling current while PWM cycles. To reduce switching loss and to get the PWM operation up to 20 kHz this device integrates fast gate drivers.

3.4 Gate Drive and Control Logic

Control logic processes the digital inputs (INA, INB, PWM, ENA/DIAGA, ENB/DIAGB). This logic blocks interpret direction commands, control switching sequences, inserts dead time automatically and manages braking modes. Its cross-conduction prevention logic ensures that high-side and low-side MOSFETs of the same leg are never on simultaneously. This protection is critical in high-current systems because shooting through currents can instantly destroy power devices..

3.5 Integrated protection subsystem

Its protection architecture is its strongest feature. For overcurrent limitation a current comparator monitors MOSFET conduction when its current exceeds threshold the device enters in current limitation mode and regulates output stage. For thermal shutdown a temperature sensor monitors junction temperature when temperature exceeds shutdown threshold its output stage disables and device waits until temperature drops below hysteresis level. For undervoltage detection, when VCC drops below safe operation voltage, MOSFET disables and prevents the unstable switching. For over voltage protection it protects against the supply spikes. For the short circuit protection it detects short to battery, short to ground, short to motor terminals and the driver reacts within microseconds to prevent damage. Lastly, for the current sensing block it integrates a proportional current sensing circuit instead of using an external shunt resistor. The advantage of this is it creates a current mirror technique ($I_{out}/I_{sense}=K$, K is a fixed scaling factor). This thing enables real time motor current monitoring, stall detection and closed loop systems.

4.0 Pin Configuration and Functional Description

4.1 Overview of Pin Structure

The VNH2SP30-E is housed in a MultiPowerSO-30 package which groups its pin in four categories

- Power supply pins
- Output power pins
- Logic control pins
- Diagnostics and current sense pins

4.2 Power Supply and output power pins

Its VCC pin provides power to the H-bridge power stage where max rating is 41v but usually used 12v to 24v. To minimize voltage ripple during switching this pin should be connected to a low-ESR bulk capacitor close to the device. If done any improper decoupling it may cause voltage spike, false overvoltage detection or EMI issues. It also provides multiple ground pins (GND_A and GND_B) to handle high return current, reduce impedance and to improve thermal dissipation. The output power pins connect directly to the motor terminal which provides high current capability, switching voltage equal to VCC also sources and sinks current. While operating one output is driven high, the other is driven low and during PWM output switches to high frequency.

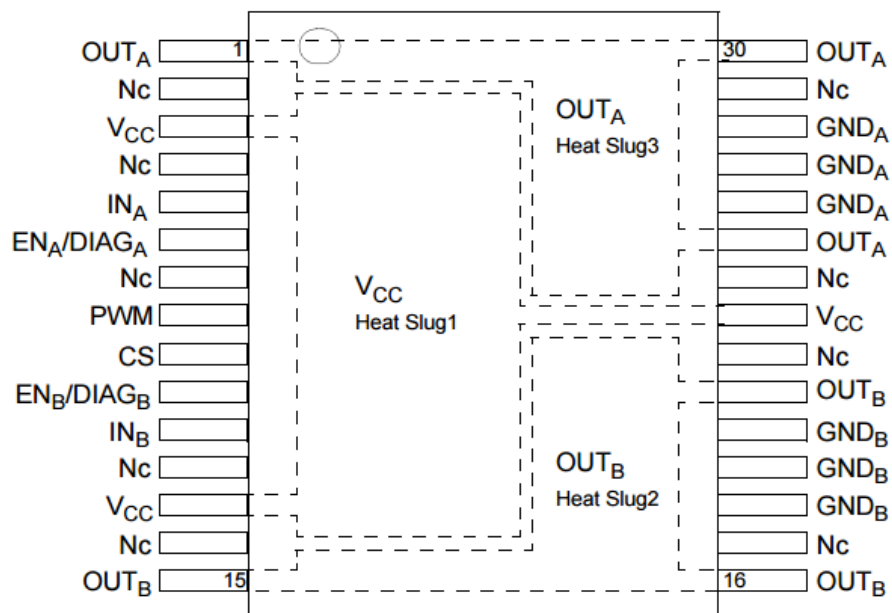


Fig 2 pin configuration

4.3 Logic Control Pins

In the logic control section the digital input (INA and INB) determines motor direction.

For forward rotation,

INA is 1 and INB is 0

For reverse rotation,

INA is 0 and INB is 1

For brake to VCC,

INA is 1 and INB is 1

For brake to GND,

INA is 0 and INB is 0

While the PWM input controls motor speed. Which accepts square wave signals with max frequency 20 kHz and controls the duty cycle of high side current. Motor speed is proportional to duty cycle.

4.4 Enable and Diagnostic Pins

The (ENA/DIAGA and ENB/DIAGB) pin serves dual purpose; it enables control for each half bridge and also provides diagnostics output during a faulty condition. Normally when pulling high channels enables and pulling low channel disables but if a faulty pin is driven low this dual function reduces pin count for more precise diagnostics external resistors can be used.

4.5 Current Sense Pin

This (CS) pin outputs a current proportional to motor load current. where ($I_{SENSE} = I_{OUT}/K$,here I_{OUT} = Motor current and K = Current sense ratio constant). This pin is connected to a resistor to ground as an ADC input of a microcontroller. Which helps in Stall detection, Overcurrent monitoring and Closed-loop torque control.

If any fault occurs in pin connection the device's power stage may be disabled, DIAG pin is pulled low, current sensing output may drop and device enters in protection mode.

5.0 Electrical Characteristics and Performance Analysis

5.1 Absolute Maximum Ratings

Absolute maximum ratings define the electrical stress limits beyond which permanent damage may occur to the VNH2SP30-E. Where key limits include VCC at 41V, maximum output current is limited by thermal constraints, Junction temperature typically up to 150°C (operational limit), Exceeding these limits shows MOSFET breakdown, thermal runaway and permanent gate oxide damage.

5.2 Recommended Operating Conditions

Under normal operating conditions its typical automotive supply is 12 V and in the Industrial system is 24 V and PWM frequency up to 20kHz. Operating in this range will ensure stable gate drive operation, proper current sensing behavior and reliable protection activation.

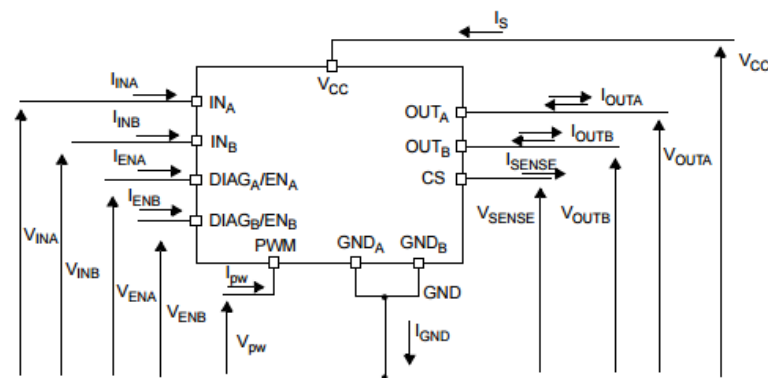


Fig 3 current and voltage conversion diagram

5.3 On-State Resistance (RDS(on)) Analysis

H-bridges total conduction loss dependent on MOSFETs on-state resistance. As the device contains both high-side MOSFETs and low-side MOSFETs. Total path resistance during conduction, $R_{total} = R_{DS(on)HS} + R_{DS(on)LS}$. Conduction power Loss which is power dissipation due to conduction, $P_{conduction} = I^2 \times R_{total}$. Which shows that power loss increases quadratically with current. For that reason If motor current doubles then conduction loss increases four times and temperature also increases that's why thermal management is critical at high current.

5.4 Switching Characteristics

During PWM operation, MOSFETs switch between on and off states. Switching losses occur during transitions because of voltage and current overlap and energy is dissipated during the

switching interval. So the switching power loss ($P_{\text{switch}} = 0.5 \times V \times I \times (t_r + t_f) \times f_{\text{PWM}}$, here t_r = rise time, t_f = fall time and f_{PWM} = switching frequency). At higher PWM frequency switching losses increases, thermal stress increases and this is why the recommended PWM frequency is limited to around 20 kHz.

5.5 Current Limitation, Under and Overvoltage Protection

The device integrates internal current limiting circuitry. When motor current exceeds threshold MOSFET gate drive reduces and output stage limits current. In that condition the device may enter regulation mode. This protects against motor stall, Short circuit and mechanical blockage. This protection reacts dynamically and automatically recovers when the fault clears.

If VCC drops below the undervoltage threshold output MOSFETs disables and the device enters safe state. This prevents incomplete MOSFET enhancement, excessive RDS(on) and uncontrolled heating.

Automotive systems experience voltage spikes due to load dump, inductive transients or alternator switching. The device includes overvoltage detection and protective mechanisms to prevent MOSFET breakdown.

5.6 Thermal Shutdown Characteristics

The device continuously monitors internal junction temperature. When temperature exceeds thermal shutdown threshold the output stage disables, DIAG pin indicates faulty. So, the device waits for cooling (hysteresis behavior). Thermal hysteresis ensures that the device does not rapidly oscillate between on and off states. This protection is essential for high-current motor applications.

5.7 Reverse Battery Protection

The VNH2SP30-E does not include internal reverse battery protection for the power stage. STMicroelectronics recommends using an external MOSFET or a diode in series with the VCC line to prevent destruction of the H-bridge if the power supply is connected backwards.

Power MOSFET - A P-channel MOSFET in series with the VCC line.

Schottky Diode - A high-current diode in series with VCC (though this incurs higher power loss).

Logic Protection - Small resistors (approximately 1k Ω) should be placed in series with the logic input pins (INA, INB, PWM) to protect the microcontroller during a reverse battery event.

6.3 PCB Layout and Thermal Management

Since this is a high-power device, the physical layout is as important as the circuit.

The MultiPowerSO-30 package uses three separate heat slugs (Slug 1 for VCC, Slug 2 for OUTB, and Slug 3 for OUTA). These must be soldered to large copper areas on the PCB to act as heat sinks.

Although the device has GNDA and GNDB pins, they are not connected internally. They must be joined together externally on the PCB to ensure a common reference and proper current return.

The junction-to-ambient thermal resistance $R_{thj-amb}$ decreases significantly as the PCB copper area increases, allowing the device to handle higher continuous currents without hitting thermal shutdown

7.0 Waveform and Timing Analysis

The typical rise time (t_r) is 1 micro sec and the typical fall time t_f is 1.2 micro sec. A vital software requirement is that the PWM signal must remain low for at least 6 micro sec during each cycle. This prevents the device's internal protection from misinterpreting the PWM switching as a "short to battery" fault. Also this device includes internal logic to minimize cross-conduction current (typically 0.7A peak) during high-frequency PWM operation.

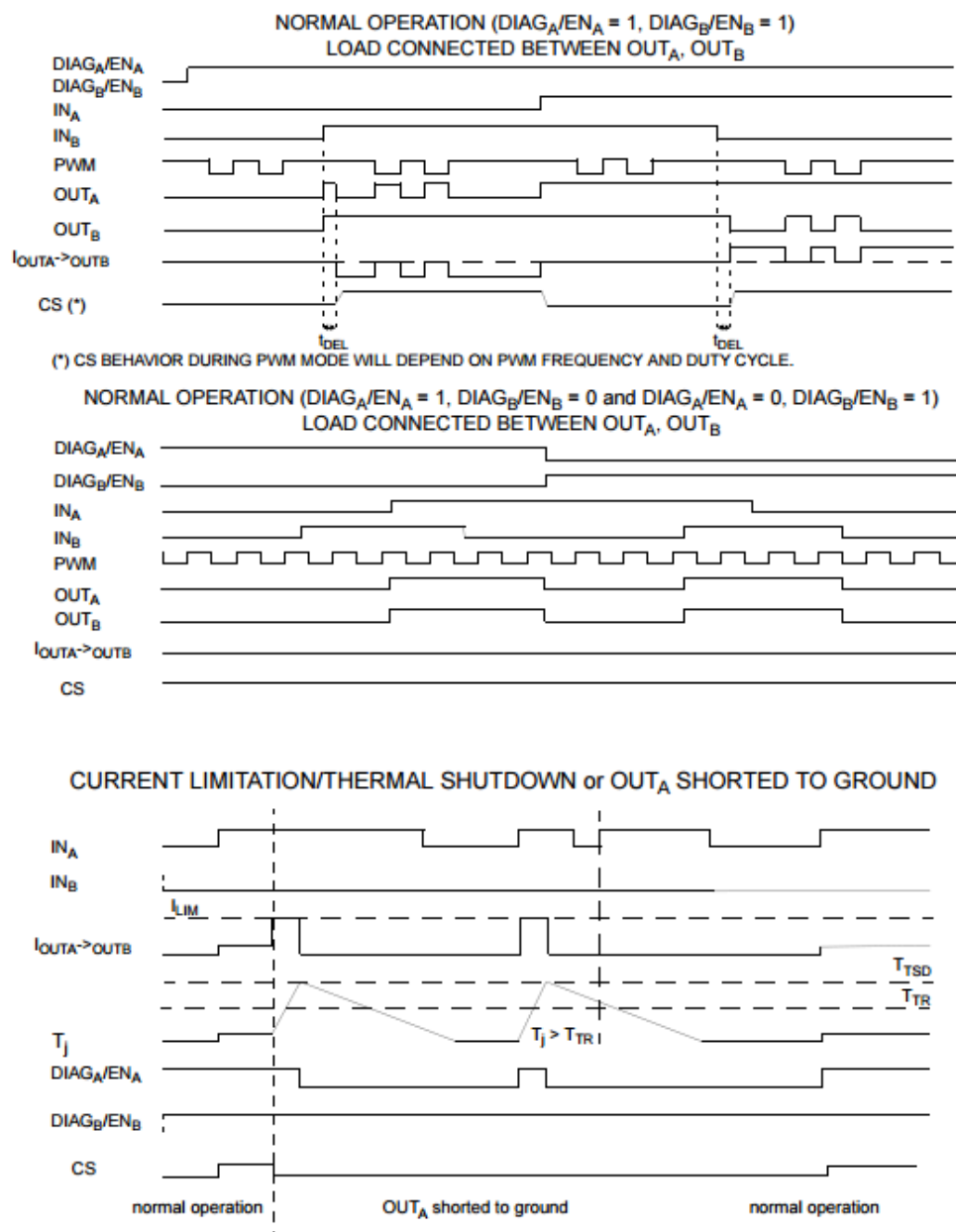


Fig 5 PWM timing diagram

8.0 Comparative Analysis of VNH2SP30-E

8.1 Advantages

1. **Integrated Protection Suite:** Unlike discrete MOSFET designs that require complex external circuitry, the VNH2SP30-E includes built-in undervoltage/overvoltage shutdown, thermal protection, and cross-conduction prevention.
2. **High Power Density:** It delivers up to 30 A of continuous current in a single MultiPowerSO-30 package, which is significantly higher than older integrated drivers like the L298N (typically limited to 2 A).
3. **Automotive Grade Reliability:** The AEC-Q100 qualification ensures the device can handle the high-vibration and extreme temperature environments common in automotive and heavy-industrial systems.
4. **Simplified Current Monitoring:** The integrated current sense (CS) pin provides a linear output proportional to motor current, eliminating the need for bulky and heat-generating external shunt resistors.
5. **Extremely Low Standby Current:** With a typical standby draw of only 12 micro A, this driver is far more efficient for battery-powered applications than most discrete H-bridge solutions.

8.2 Limitations and Trade-offs (Cons)

1. **PWM Frequency Limit:** The device is optimized for PWM operation up to 20 kHz. While sufficient for most applications, some modern high-performance drivers or discrete designs can exceed 50 kHz for ultra-quiet operation.
2. **Voltage Range Constraints:** Designed primarily for 12V automotive systems, the operating range is 5.5 V to 24 V. Industrial applications requiring 48 V or more operation would require a different driver.
3. **Minimum PWM Off-Time:** To avoid false "short-to-battery" fault detection, the PWM signal must remain low for at least 6 micro sec per cycle, which can limit the maximum effective duty cycle at high frequencies.
4. **External Reverse Battery Protection:** While the device protects itself from many faults, it does not include internal reverse battery protection for the power stage, requiring an external MOSFET or diode for full system safety.

Conclusion

The VNH2SP30-E motor driver by STMicroelectronics is a high-performance, integrated H-bridge solution suitable for both automotive and industrial DC motor applications. Its combination of high-current capability, integrated MOSFETs, gate drivers, and robust protection features significantly simplifies motor control designs while improving reliability and efficiency. Key advantages include precise current sensing, thermal and overcurrent protection, and automotive-grade qualification (AEC-Q100), making it highly suitable for high-torque and battery-powered systems.

While limitations such as PWM frequency constraints, voltage range, and lack of internal reverse battery protection require careful design consideration, these disadvantages are manageable with proper PCB layout and external circuitry. Overall, the VNH2SP30-E provides a compact, efficient, and reliable solution for modern embedded motor control applications, reducing external component count and ensuring safe operation under demanding conditions.